

Industry – smallest on-board area and low-profile construction enhance board design freedom.

- Occupies smallest on-board area in the industry.
- Low profile only 1.2 mm max. above the board.
- Connector terminals on the lower surface are not exposed achieving high board-design efficiency
- Secure locking
- Applicable FPC thickness, $t = 0.3\text{mm}$



Specifications

■ Specifications

Rated Current	0.5A AC/DC
Rated Voltage	50V AC/DC
Contact resistance	30 mΩ max. (max. 20 mV, 100 mA)
Insulation resistance	100 MΩ min. (at 250 VDC)
Withstand voltage	250 VAC 1 min. (leakage current: 1 mA max.)
Insertion tolerance	20 times
Ambient temperature	-30 to +85°C (No condensation at low temperatures.)

■ Materials/Finish

	Upper Contact Type	Lower Contact Type
Housing	LCP Resin (UL94V-0)/natural	
Slider	LCP resin (UL94V-0)/black	LCP resin UL94V-0)/brown
Contact	Spring copper-alloy/nickel substrate (2μm)/gold plated contacts (0.15 μm)	
Hold-down	Spring copper-alloy/fused-tin plating (1.5μm)	

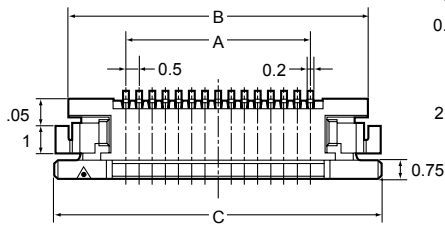
■ Ordering Information

Poles	Type	Model (note 1)	Poles	Type	Model (note 1)	Quantity per reel
4	Upper Contact	XF2L-0425-1 □	13	Upper Contact	XF2L-1325-1 □	3,000
5	Lower Contact	XF2L-0535-1 □		Lower Contact	XF2L-1335-1 □	
6	Upper Contact	XF2L-0625-1 □	15	Lower Contact	XF2L-1535-1 □	
	Lower Contact	XF2L-0635-1 □		18	Upper Contact	
7	Upper Contact	XF2L-0725-1 □	19		Lower Contact	
	Lower Contact	XF2L-0735-1 □		20	Lower Contact	
8	Upper Contact	XF2L-0825-1 □	21		Lower Contact	
	Lower Contact	XF2L-0835-1 □		22	Upper Contact	
9	Upper Contact	XF2L-0925-1 □	24		Lower Contact	
10	Upper Contact	XF2L-1025-1 □		26	Lower Contact	
	Lower Contact	XF2L-1035-1 □	30		Upper Contact	
12	Upper Contact	XF2L-1225-1 □		30	Lower Contact	
	Lower Contact	XF2L-1235-1 □	Upper Contact		XF2L-3025-1 □	
				Lower Contact	XF2L-3035-1 □	

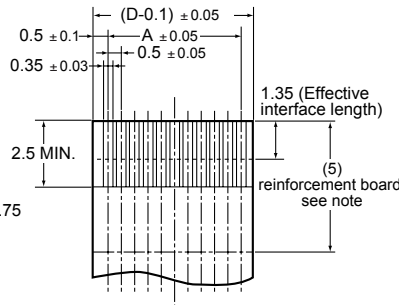
Note 1: According to the stated specifications, the aperture at the end of the unit shall be plated
 A: Gold-plated (lead-free)
 L: Lead solder (tin-lead SnPb alloy solder)
 Soldering plate specifications will apply until March 2006.

■ Dimensions

XF2L-□□□5-1□

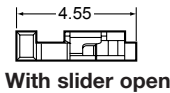
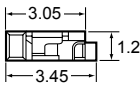
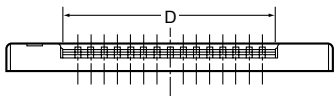


Applicable FPC Dimensions

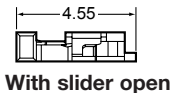
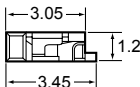
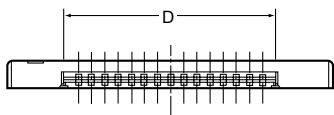


Note 1: Use polyimide and thermoset adhesive for reinforcement film material.

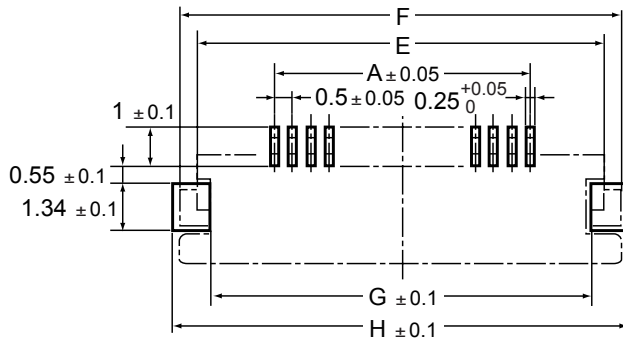
XF2L-□□25-1 (Upper Contact Type)



XF2L-□□35-1 (Lower Contact Type)



Printed Circuit Board Matching Dimension (Top View)



■ Table of Dimensions

Upper Contact Type

Poles	Model	A	B	C	D	E	F	G	H
4	XF2L-0425-1 □	1.5	5.9	6.9	2.6	5.88	6.88	5.28	7.28
6	XF2L-0625-1 □	2.5	6.9	7.9	3.6	6.88	7.88	6.28	8.28
7	XF2L-0725-1 □	3.0	7.4	8.4	4.1	7.38	8.38	6.78	8.78
8	XF2L-0825-1 □	3.5	7.9	8.9	4.6	7.88	8.88	7.28	9.28
9	XF2L-0925-1 □	4.0	8.4	9.4	5.1	8.38	9.38	7.78	9.78
10	XF2L-1025-1 □	4.5	8.9	9.9	5.6	8.88	9.88	8.28	10.28
12	XF2L-1225-1 □	5.5	9.9	10.9	6.6	9.88	10.88	9.28	11.28
13	XF2L-1325-1 □	6.0	10.4	11.4	7.1	10.38	11.38	9.78	11.78
18	XF2L-1825-1 □	8.5	12.9	13.9	9.6	12.88	13.88	12.28	14.28
21	XF2L-2125-1 □	10.0	14.4	15.4	11.1	14.38	15.38	13.78	15.78
26	XF2L-2625-1 □	12.5	16.9	17.9	13.6	16.88	17.88	16.28	18.28
30	XF2L-3025-1 □	14.5	18.9	19.9	15.6	18.88	19.88	18.28	20.28

Lower Contact Type

Poles	Model	A	B	C	D	E	F	G	H
5	XF2L-0535-1 □	2.0	6.4	7.4	3.1	6.38	7.38	5.78	7.78
6	XF2L-0635-1 □	2.5	6.9	7.9	3.6	6.88	7.88	6.28	8.28
7	XF2L-0735-1 □	3.0	7.4	8.4	4.1	7.38	8.38	6.78	8.78
8	X2FL-0835-1 □	3.5	7.9	8.9	4.6	7.88	8.88	7.28	9.28
10	XF2L-1035-1 □	4.5	8.9	9.9	5.6	8.88	9.88	8.28	10.28
12	XF2L-1235-1 □	5.5	9.9	10.9	6.6	9.99	10.88	9.28	11.28
13	XF2L-1335-1 □	6.0	10.4	11.4	7.1	10.38	11.38	9.78	11.78
15	XF2L-1535-1 □	7.0	11.4	12.4	8.1	11.38	12.38	10.78	12.78
18	XF2L-1835-1 □	8.5	12.9	13.9	9.6	12.88	13.88	12.28	14.28
19	XF2L-1935-1 □	9.0	13.4	14.4	10.1	13.38	14.38	12.78	14.78
20	XF2L-2035-1 □	9.5	13.9	14.9	10.6	13.88	14.88	13.28	15.28
22	XF2L-2235-1 □	10.5	14.9	15.9	11.6	14.88	15.88	14.28	16.28
24	XF2L-2435-1 □	11.5	15.9	16.9	12.6	15.88	16.88	15.28	17.28
30	XF2L-3035-1 □	14.5	18.9	19.9	15.6	18.88	19.88	18.28	20.28